Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]

HP RP9 G1 AiO Retail System, Model 9018

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps N/A</td>
<td>2</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>N/A</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td>N/A</td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances | N/A | 0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Hexagonal Screwdriver (T15)</td>
<td>T15 2.55-3.00kgf.cm</td>
</tr>
<tr>
<td>Philips Screwdriver</td>
<td>2# 2.55-3.00kgf.cm</td>
</tr>
<tr>
<td>Knife</td>
<td></td>
</tr>
<tr>
<td>Side Cutter</td>
<td></td>
</tr>
<tr>
<td>Star key wrench</td>
<td></td>
</tr>
<tr>
<td>Slotted Screwdriver</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassembly process – Removing Back Cover
2. Disassembly process – Installing Wireless Card
3. Disassembly process – Installing DIMM
4. Disassembly process – Do not remove the HDD cage
5. Disassembly process – Remove the HDD cage
6. Disassembly process (CPU Installing)
7. Disassembly process (Installing back cover bracket)
8. Disassembly process (Assemble MCR, webcam, BIO reader (If necessary)
9. Disassembly process (MSR, Webcam, BIO)
10. Disassembly process (Assemble back cover)
11. Compact Stand Assembling (Without Power Supply)
12. 

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Description of the sample submitted for assessment
Disassembly process (Removing Back Cover)
Push the button on the middle bezel to each side, see photo 1.

Disassemble the back cover by pulling it upward and cover, see photo 2.

Take off the rear cover, see photo 3.

Disassemble the bracket, see photo 4.

Disassemble the bracket by the red circle marked position and take off the bracket, see photo 5.

Lift up the bracket, see photo 6.

Pressing the visa cover hook and push it to the direction show in the photo 7, 8 and 9.

Disassembly process (Installing Wireless Card)
Install the wireless card at an angle of 45 degree. See photo 1.

Fasten WIFI screw*1pcs as shown in photo 2. 1.5 +/- 0.2Kgf.cm Screwdriver: #1 (Crosshead Screwdriver). See photo 2.


Disassembly process (Installing DIMM)

Take the DIMM and insert in DIMM slot at an angle of 45 degree. See photo 1.

Press the DIMM to confirm the DIMM insert rightly. See photo 2.

Disassembly process (Do not remove the HDD cage)
Unlocking the 2 screws on the HDD bracket see photo 1 (T15) 3.0+/-.0.3kgf.cm

Lift up the HDD bracket horizontally and take down the HDD bracket, see photo 2,3

Assemble the second SSD Card to the SSD2 mark connector, and fix the SSD card to the unit by lock the screw, see photo 4

Assemble the first SSD Card to the SSD1 mark connector, and fix the SSD card to the unit by lock the screw, see photo 3
Assembling the HDD bracket to the unit and lock the 2pcs screws, see photo 6 (T15) 3.0+/−0.3kgf.cm

Disassembly process (Do not remove the HDD cage)

Assemble the first SSD Card to the SSD1 mark (left position) connector by one hand, and hold the Mylar by another hand, see photo 1

Press the SSD to confirm it insert rightly, and lock the screw to fix the SSD on the MB, pull the Mylar aside at same time, see photo 2
HDD Module Processing and Installing (if necessary)

Do not remove the HDD cage

- Remove the tape on the HDD cage. See photo 1.
- Take 4 screws to lock the HDD, (#1) 1.5 +/- 0.3 kgf·cm. See photo 2.
- Pull the HDD holder splinter outwards, and assemble the HDD rightly. See photo 4.
- Slide the HDD holder splinter and assemble the HDD to the HDD cage rightly. See photo 4.
- Insert the SATA cable to the HDD. See photo 5.
- Check the connector is inserted rightly. See photo 6.

Disassembly process (Remove the HDD cage)

PSG instructions for this template are available at EL-MF877-01
Unscrew the 2 screws and remove the HDD bracket. See photo 1 and 2.

Take 4 screws to lock the HDD. (#1) 1.5 +/- 0.3 kgf.cm. See photo 3.

Install HDD in the unit. See photo 4.

Check the Mylar connected to the MB rightly. See photo 6.

Insert the HDD SATA cable to HDD. See photo 5.

Disassembly process (CPU Installing)
Open the CPU cover and take off the plastic cover, check whether there is PIN bend issue, See photo 2 for the bend pin.

Put the CPU onto the CPU socket vertical by fixture, see photo 3 and 4.

Locking the CPU holder, and during this process, the CPU holder clip will drop from the CPU holder, take clip away from the MB, see photo 5 and 6.

Lock the heat sink to MB, and lock the 3 screws based on the sequence shown on heat sink, see photo 7 and 8.

Disassembly process (Installing visa cover)
Align the visa cover to the bracket and press the clip to lock on to the bracket, see photo 1.

Confirm the visa cover locked well, see photo 2 and 3.

---

**Disassembly process (Installing back cover bracket)**

Align the rear cover to the unit by the two latch, see photo 1.

Push the rear cover to end, see picture 2.

Press the latch and confirm locked, see photo 4.

---

**Disassembly process (Assemble MCR, webcam, BIO reader (If necessary))**

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Unscrew the 2 screws on the 3 dummy covers, see photo 1 and 2

Put one screwdriver head into the screw hole and pull the dummy cover outward, use same method to disassemble the 3 dummy covers

Lock the 2 screws, see photo 6

Assemble the Webcam, MSR,BIO to the unit and lock the two screw red marked See Photo 4. Confirm the Webcam, MSR,BIO assembled rightly see photo 5

Disassembly process (MSR, Webcam, BIO)
After the MSR, Webcam, BIO assembled status, see photo 1

---

**Disassembly process (Assemble back cover)**

Put the back cover to the unit. See photo 1

Push it towards your self-direction. See photo 2

Assemble the back cover to the unit, and lock the hook. See photo 3

Double check and confirm all the hooks are locked well. See photo 4

---

**Compact Stand Assembling (Without Power Supply)**

PSG instructions for this template are available at [EL-MF877-01](#)
Assemble the bottom cover to the stand, see photo 1~2

Check the 6 latches on the cover are no damage, see photo 4

Assemble the bottom cover to the stand, see photo 3

Assemble the stand to the unit
Lock each hook of the stand to the unit VESA cover socket, 1 to 1, 2 to 2 see photo 5